ENCAPSULATION OPTIONS

Advantages:

• Choose the encapsulation style that meets your prototyping needs
• Mix & match multiple encapsulation options on the same assembly order
• Assembly turn times from 8 hours to 3 days available

Flattened/Remolded (fully encapsulated with filled epoxy utilizing Quik-Pak proprietary molding process)
  • Test socket compatible/meets JEDEC mechanical standards
  • Suitable for customer samples, pre-production runs, etc.
  • Auto handling compliant
  • Electrical performance equivalent to production package
  • Optional marking / branding service available

Glob Top (fully encapsulated with filled epoxy – domed top surface)
  • Electrical performance equivalent to production package
  • Optional marking/branding service available
  • Suitable for chip-on-board applications

Partial Open Cavity (encapsulated with filled epoxy in selected areas)
  • FIB ready, uV erasable
  • Ideal for circuit repair, visual inspection, emission studies, etc.
  • Wires partially protected from mechanical damage

Open Cavity with Frame or Lid (no encapsulant, custom frame and/or lid)
  • Die & wires protected, yet accessible
  • Ease of probing die & chip
  • Test socket compatible
  • FIB ready, uV erasable
  • Ideal for circuit repair, visual inspection, emission studies, etc.
  • Suitable for MEMS applications

Open Cavity (wire bonded chip with no encapsulant, die is exposed)
  • Ease of probing die & chip
  • FIB ready, uV erasable
  • Ideal for circuit repair, visual inspection, emission studies, etc.

Clear Encapsulant (encapsulated with non-filled epoxy)
  • Easy wire bonding verification
  • Visual sample of assembled product
  • Eliminates need for X-Ray wire length measurements
  • Lower dielectric constant
  • Suitable for IR or visual light transmission applications